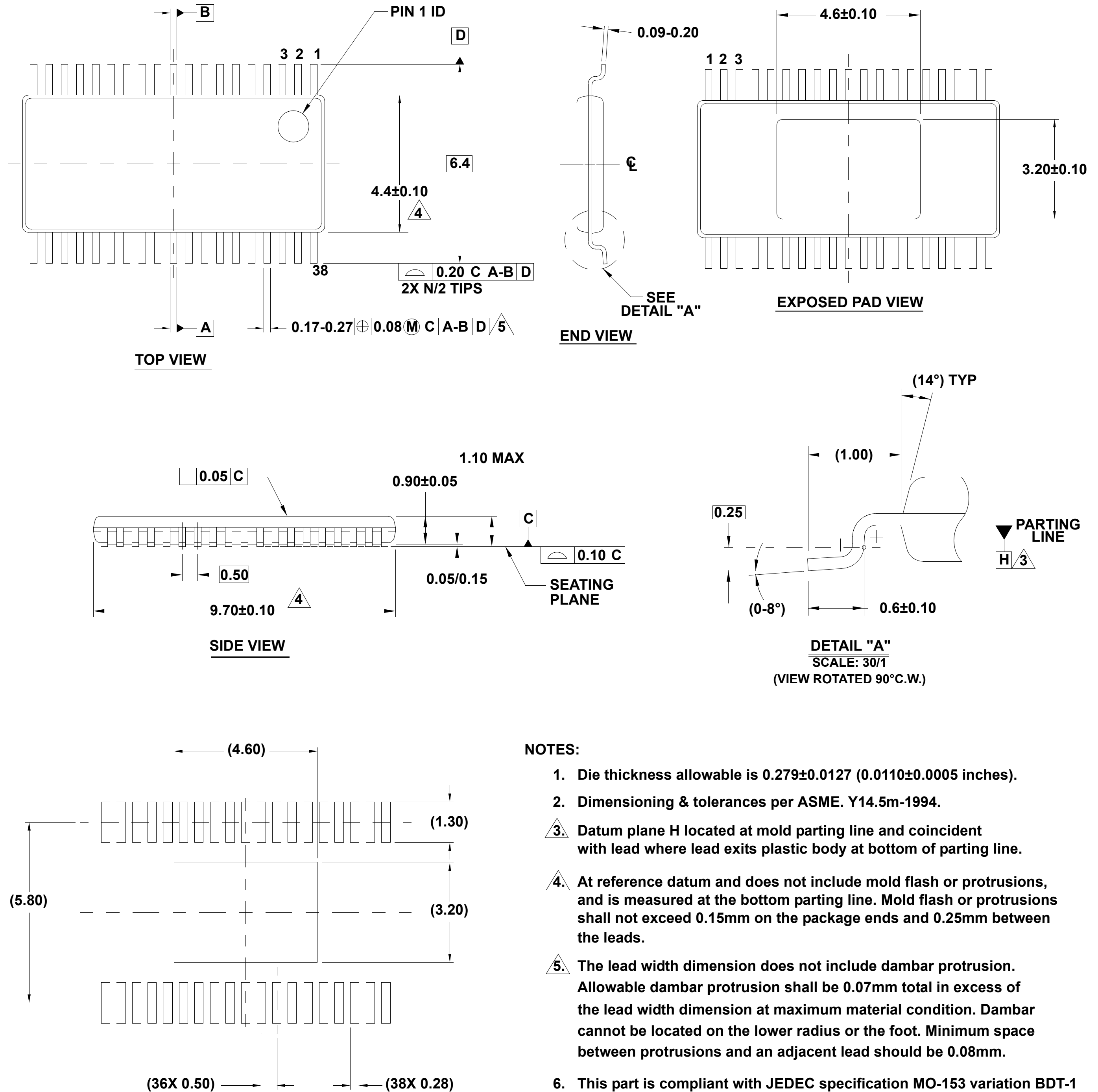
Package Outline Drawing

M38.173C

38 LEAD HEAT-SINK THIN SHRINK SMALL OUTLINE PLASTIC PACKAGE (HTSSOP)
Rev 0, 4/10



NOTES:

1. Die thickness allowable is 0.279±0.0127 (0.0110±0.0005 inches).
2. Dimensioning & tolerances per ASME. Y14.5m-1994.
3. Datum plane H located at mold parting line and coincident with lead where lead exits plastic body at bottom of parting line.
4. At reference datum and does not include mold flash or protrusions, and is measured at the bottom parting line. Mold flash or protrusions shall not exceed 0.15mm on the package ends and 0.25mm between the leads.
5. The lead width dimension does not include dambar protrusion. Allowable dambar protrusion shall be 0.07mm total in excess of the lead width dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot. Minimum space between protrusions and an adjacent lead should be 0.08mm.
6. This part is compliant with JEDEC specification MO-153 variation BDT-1